5-104666-1 ACTIVE

AMPMODU | AMPMODU System 50

TE Internal #: 5-104666-1

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder,

AMPMODU System 50

View on TE.com >

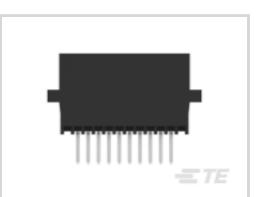


Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical
Connector System: Board-to-Board

Number of Positions: 20
Number of Rows: 2

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-----------------------|
| Connector System | Board-to-Board |
| Header Type | Fully Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |

Configuration Features

| Connector Contact Load Condition | Fully Loaded |
|----------------------------------|--------------|
| PCB Mount Orientation | Vertical |
| Number of Positions | 20 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |

Electrical Characteristics

| Dielectric Withstanding Voltage (Max) | 500 VAC |
|---------------------------------------|---------|
| Insulation Resistance | 5000 ΜΩ |



| Operation a Valtage | 20 \/ \ C |
|---|-------------------------------|
| Operating Voltage | 30 VAC |
| Body Features | |
| Connector Profile | Standard |
| Primary Product Color | Black |
| Contact Features | |
| Mating Square Post Dimension | .38 mm[.015 in] |
| PCB Contact Termination Area Plating Material Thickness | 3.81 – 6.35 μm[150 – 250 μin] |
| PCB Contact Termination Area Plating Material Finish | Matte |
| Contact Shape & Form | Rectangular |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .76 μm[30 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3.6 A |
| Termination Features | |
| Round Termination Post & Tail Diameter | .38 mm[.015 in] |
| Termination Post & Tail Length | 3.68 mm[.145 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Retention | With |
| Mating Retention Type | Latching |
| Mating Alignment | With |
| Mating Alignment Type | Polarization |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 1.27 mm[.05 in] |
| Housing Material | LCP |
| Dimensions | |
| | |



| Row-to-Row Spacing | 2.54 mm[.1 in] |
|-----------------------------|----------------------------|
| PCB Thickness (Recommended) | 1.57 mm[.062 in] |
| Usage Conditions | |
| Housing Temperature Rating | High |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| UL Rating | Recognized |
| Agency/Standard | CSA, UL |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 27 |
| Packaging Type | Box, Tube |
| Other | |
| | |

Product Compliance

Position Locations Omitted

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Wave solder capable to 260°C |
| Product Compliance Disclaimer | |

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This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts











Also in the Series | AMPMODU System 50



Customers Also Bought

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50















Documents

Product Drawings

20 SYSTEM 50 HDR DRST SHRD SN

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-104666-1_AD.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_5-104666-1_AD.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-104666-1_AD.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English

Product Specifications

Application Specification

English

Product Environmental Compliance

TE Material Declaration

PCB Mount Header, Vertical, Board-to-Board, 20 Position, 1.27 mm [.05 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU System 50



English